

S/N 09/751,614

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Phil Geng et al.

Examiner: Jose H. Alcala

Serial No.: 09/751,614

Group Art Unit: 2827

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Docket No.: 884.387US1

Title: VIA-IN-PAD WITH OFF-CENTER GEOMETRY AND METHODS OF
MANUFACTURE

Assignee: Intel Corporation

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants have reviewed the Office Action mailed on May 6, 2003. Please amend the above-identified patent application as follows.

